

Part Number: **DZQA5V6AXV5-p**
Weight (mg): 3.452

p = package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	2.07	0.0715	1000000	20713
Leadframe	CDA-194	Cu	7440-50-8	97.40%	45.53	1.5717	974000	443463
		Fe	1309-37-1	2.40%			24000	10927
		P	7723-14-0	0.08%			800	364
		Zn	7440-66-6	0.12%			1200	546
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.46	0.0158	1000000	4577
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.14	0.0394	1000000	11414
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	48.19	1.6636	873000	420719
		Epoxy Resin	29690-82-2	5.00%			50000	24096
		Phenol Resin	26834-02-6	5.00%			50000	24096
		Aromatic poly-phosphate	----	2.50%			25000	12048
		C	1333-86-4	0.20%			2000	964
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.83	0.0288	750000	6257
		epoxy resin	Trade secret	20.00%			200000	1669
		curing agent & hardener	Trade secret	5.00%			50000	417
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.77	0.0612	1000000	17729
					Total	100.00	3.452	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentaoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate